

## 論文著述：

### A. 期刊論文

1. S. J. Grafner, P. Y. Wu, and C. R. Kao\*, "Flow in a Microchannel Filled with Arrays of Numerous Pillars," *International Journal of Heat and Fluid Flow*, 97, 109045, **2022**.
2. Wei-Chen Huang, Chin-Hao Tsai, Pei Tzu, Lee, and C. R. Kao\*, "Effects of Bonding Pressures on Microstructure and Mechanical Properties of Silver–Tin Alloy Powders Synthesized by Ball Milling for High-Power Electronics Packaging," *Journal of Materials Research and Technology*, 19, p.3828-3841, **2022**.
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9. S. Maheshwaran, V. Renganathan, Shen-Ming Chen\*, R. Balaji, C. R. Kao\*, N. Chandrasekar, S. Ethiraj, M. S. Samuel, M. Govarthanan, "Hydrothermally Constructed AgWO<sub>4</sub>-rGO Nanocomposites as an Electrode Enhancer for Ultrasensitive Electrochemical Detection of Hazardous Herbicide Crisquat," *Chemosphere*, 299, 134434, **2022**.
10. V. Renganathan, R. Balaji, S. M. Chen, N. Chandrasekar, S. Maheshwaran, and C. R. Kao, "Bifunctional nanocomposites based on SiO<sub>2</sub>/NiS<sub>2</sub> combination for electrochemical sensing and environmental catalysis," *Electroanalysis*, 34, p.111-121, **2022**.
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